

SEMITOP® 3

IGBT Module

SK20GD066ET

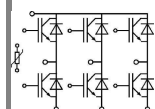
Target Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Trench IGBT technology
- CAL technology FWD
- Integrated NTC temperature sensor

Typical Applications*

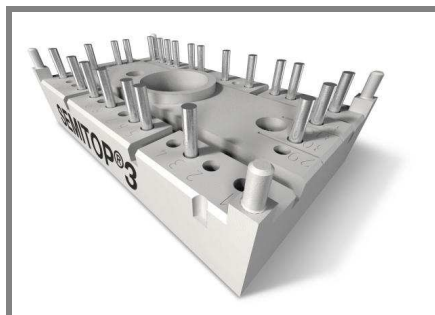
- Inverter up to 6,3 kVA
- Typ. motor power 4 kW



GD-ET

Absolute Maximum Ratings				$T_s = 25\text{ °C}$, unless otherwise specified	
Symbol	Conditions			Values	Units
IGBT					
V_{CES}	$T_j = 25\text{ °C}$			600	V
I_C	$T_j = 175\text{ °C}$	$T_s = 25\text{ °C}$		30	A
		$T_s = 70\text{ °C}$		25	A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$			40	A
V_{GES}				± 20	V
t_{psc}	$V_{CC} = 360\text{ V}$; $V_{GE} \leq 20\text{ V}$; $T_j = 150\text{ °C}$ $V_{CES} < 600\text{ V}$			6	μs
Inverse Diode					
I_F	$T_j = 175\text{ °C}$	$T_s = 25\text{ °C}$		31	A
		$T_s = 70\text{ °C}$		24	A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$			40	A
I_{FSM}	$t_p = 10\text{ ms}$; half sine wave $T_j = 150\text{ °C}$			95	A
Module					
$I_{t(RMS)}$					A
T_{vj}				-40 ... +175	$^{\circ}\text{C}$
T_{stg}				-40 ... +125	$^{\circ}\text{C}$
V_{isol}	AC, 1 min.			2500	V

Characteristics			T _s = 25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 0,29 mA		5	5,8	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _J = 25 °C T _J = 125 °C	0,0011			mA mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V	T _J = 25 °C T _J = 125 °C	300			nA nA
V _{CE0}		T _J = 25 °C T _J = 150 °C		0,9 0,8	1,1 1	V V
r _{CE}	V _{GE} = 15 V	T _J = 25°C T _J = 150°C		27,5 42,5	37,5 52,5	mΩ mΩ
V _{CE(sat)}	I _{Cnom} = 20 A, V _{GE} = 15 V	T _J = 25°C _{chiplev.} T _J = 125°C _{chiplev.}		1,45 1,65	1,85 2,05	V V
C _{ies} C _{oes} C _{res}	V _{CE} = 25, V _{GE} = 0 V	f = 1 MHz		1,1 0,071 0,032		nF nF nF
Q _G	V _{GE} = -7V...+15V			225		nC
t _{d(on)} t _r E _{on}	R _{Gon} = 15 Ω di/dt = 3300 A/μs	V _{CC} = 300V I _C = 20A		16 15 0,34		ns ns mJ
t _{d(off)} t _f E _{off}	R _{Goff} = 15 Ω di/dt = 3300 A/μs	T _J = 150 °C V _{GE} =±15V		166 40 0,63		ns ns mJ
R _{th(j-s)}	per IGBT			1,95		K/W



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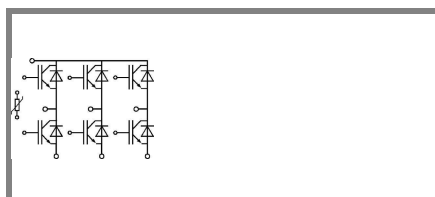
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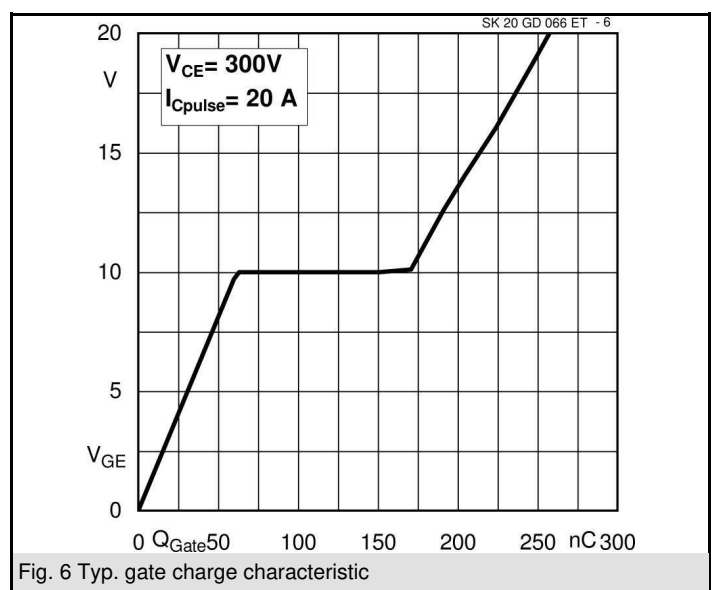
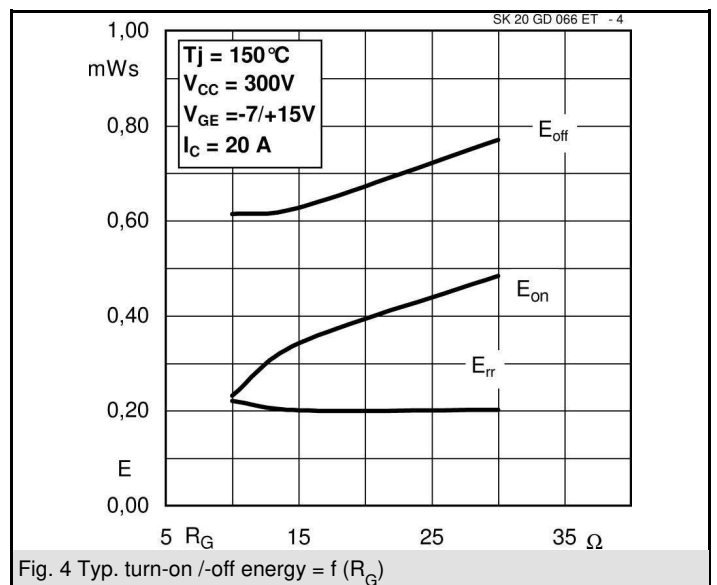
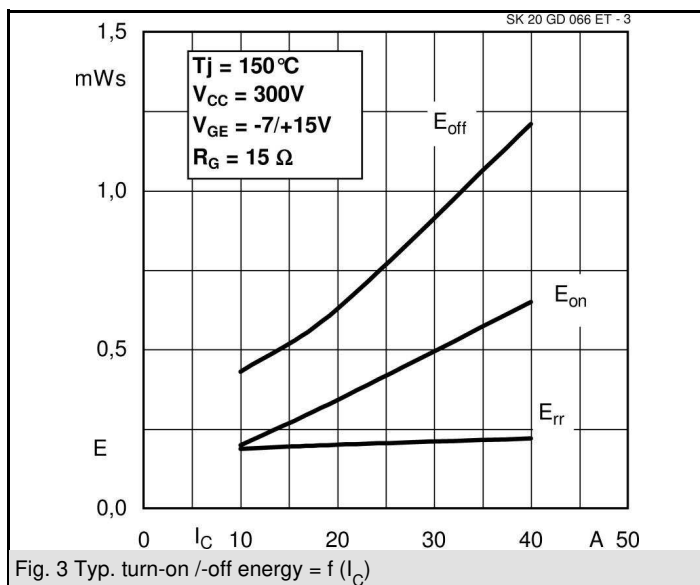
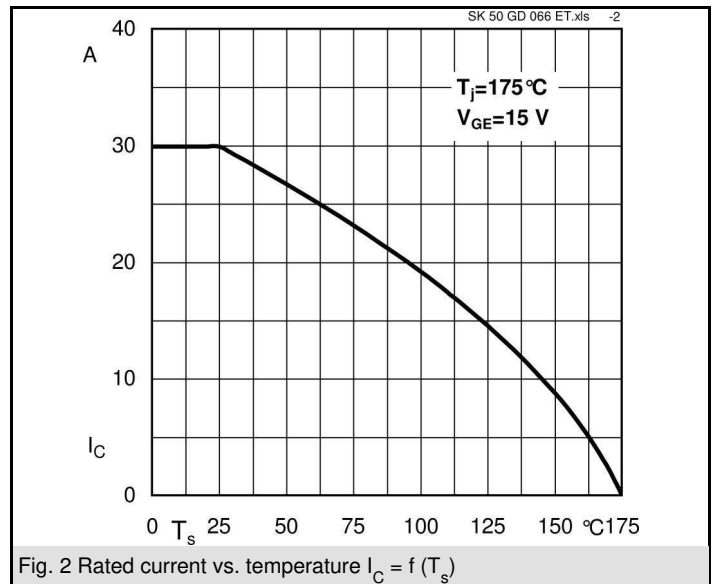
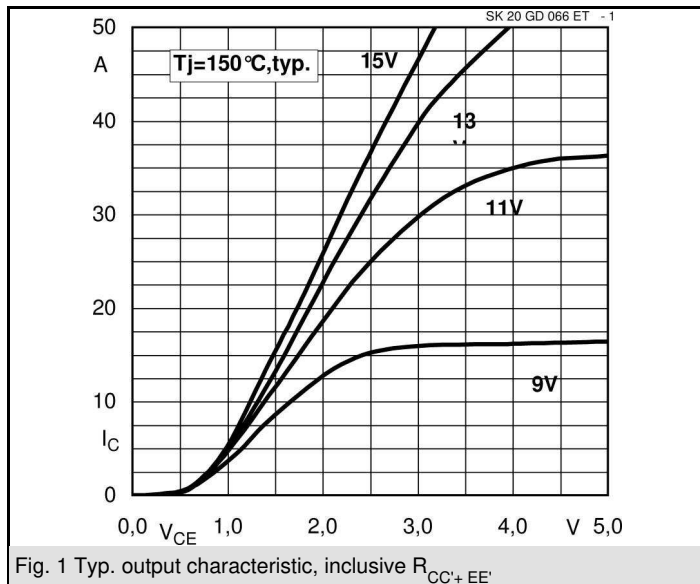
Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
V _F = V _{EC}	I _{Fnom} = 20 A; V _{GE} = 0 V	T _j = 25 °C _{chiplev.}	1,45	1,7	V
		T _j = 150 °C _{chiplev.}	1,45	1,7	V
V _{F0}		T _j = 25 °C	1	1,1	V
		T _j = 150 °C	0,9	1	V
r _F		T _j = 25 °C	22,5	30	mΩ
		T _j = 150 °C	27,5	35	mΩ
I _{RRM}	I _F = 30 A	T _j = 150 °C	32		A
Q _{rr}	di/dt = 3300 A/μs		2		μC
E _{rr}	V _{CC} = 300V		0,2		mJ
R _{th(j-s)D}	per diode		2,46		K/W
M _s	to heat sink	2,25		2,5	Nm
w			30		g
Temperature sensor					
R ₁₀₀	T _s =100°C (R ₂₅ =5kΩ)		493±5%		Ω

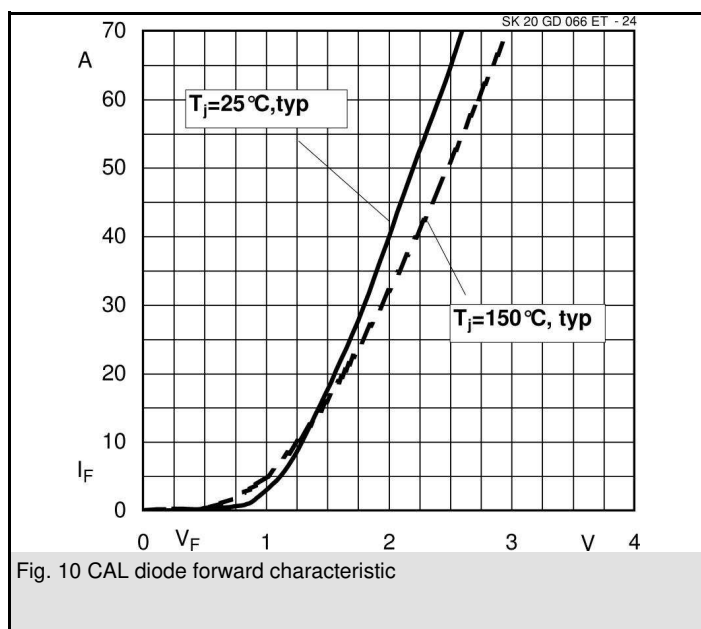
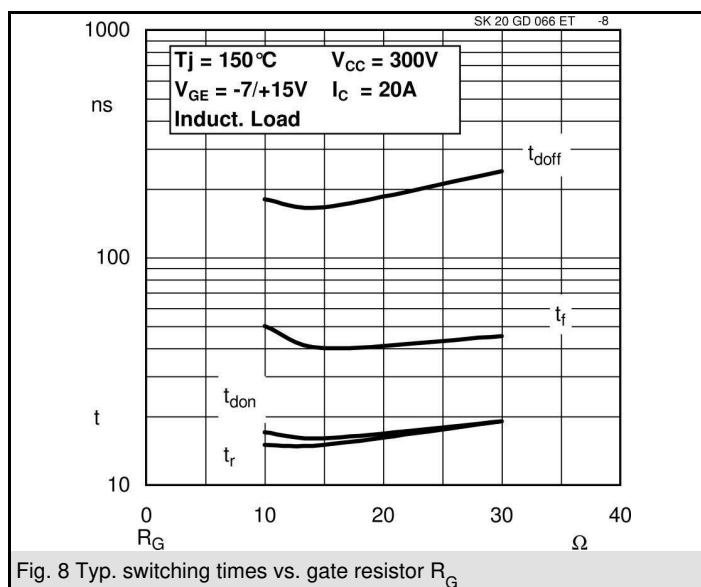
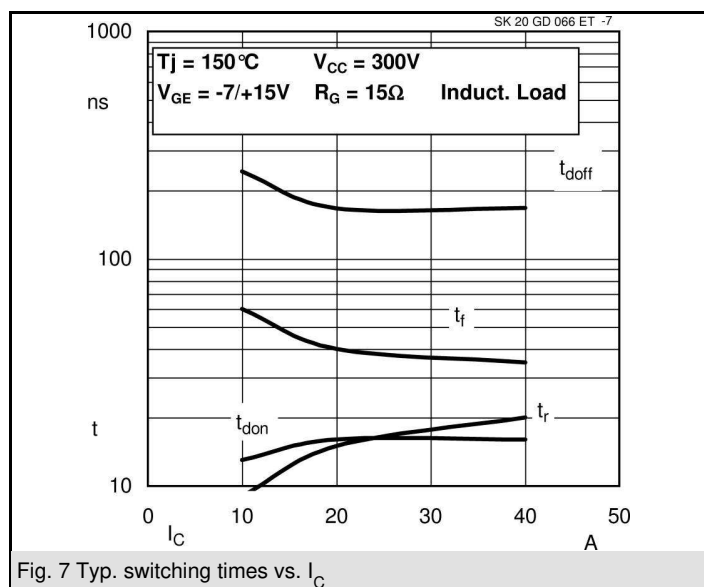
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

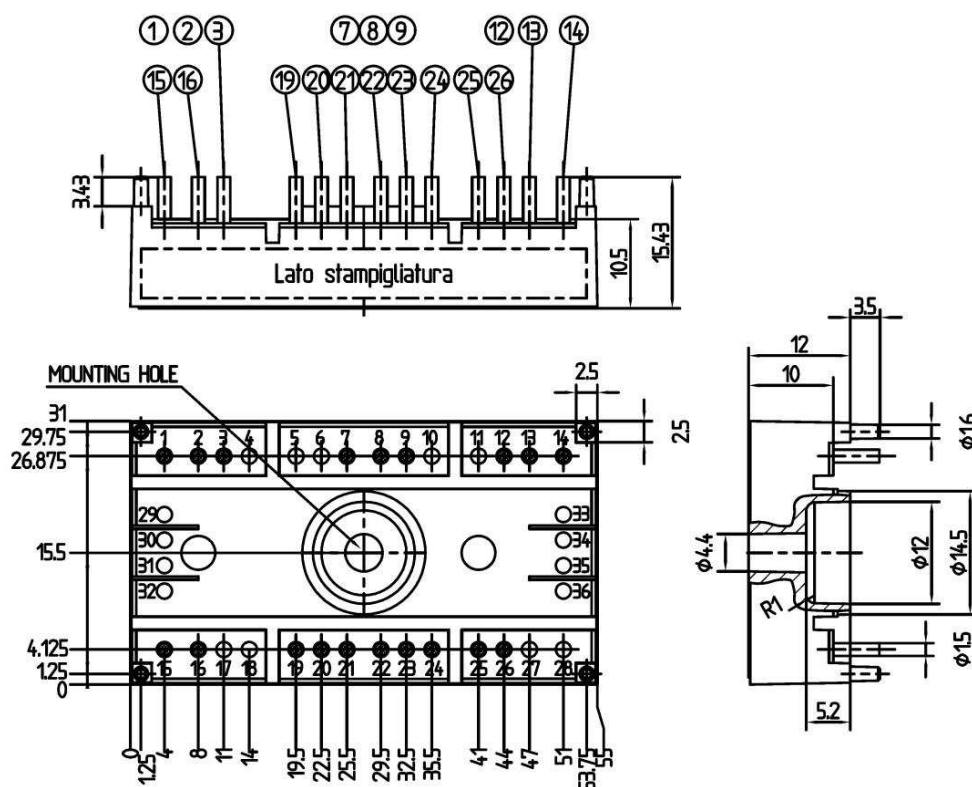
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.



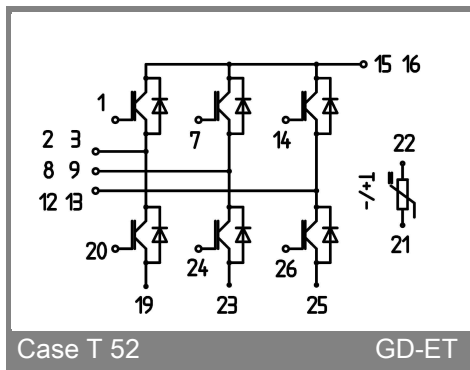
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Case T52 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 52

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